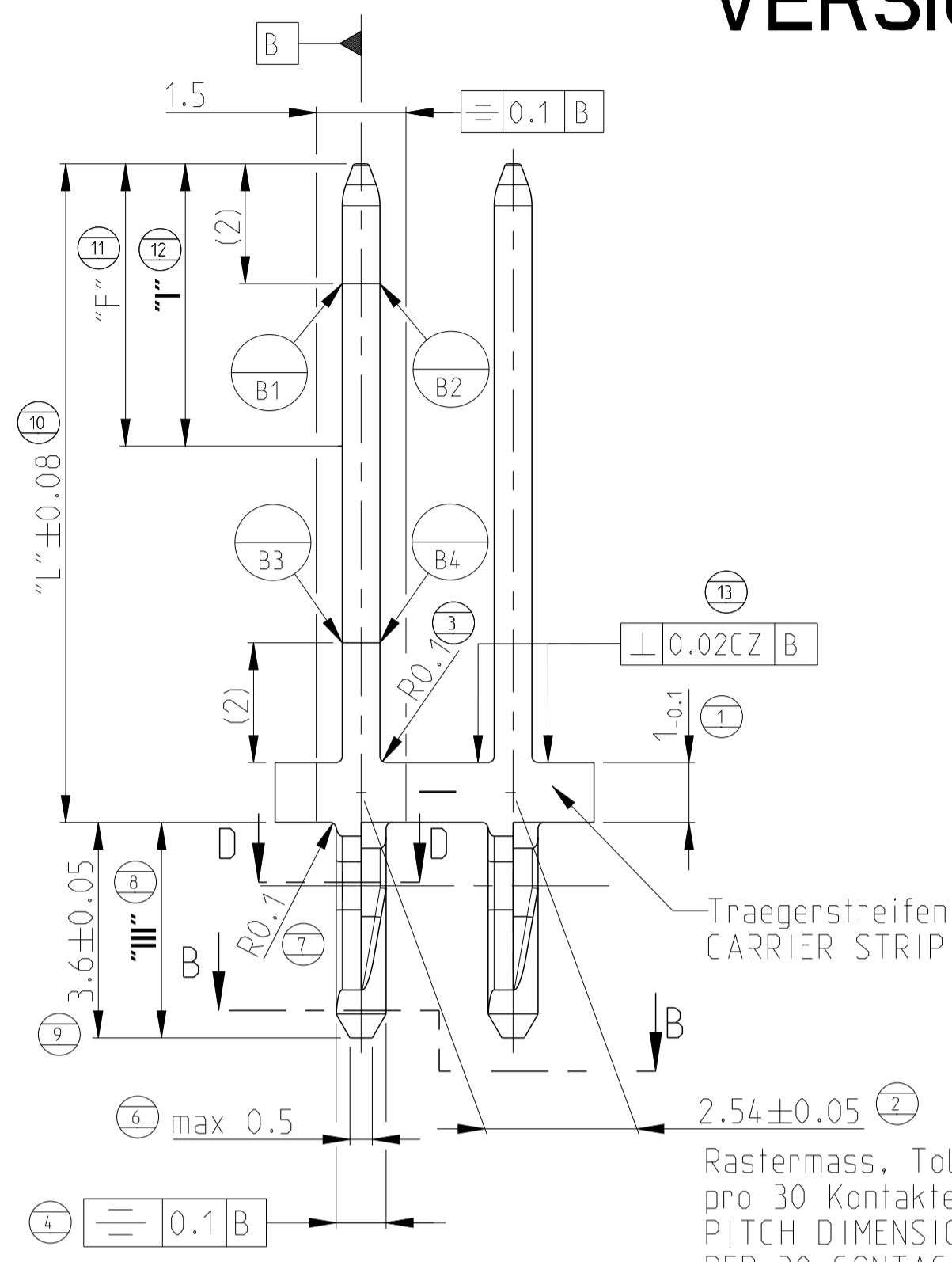
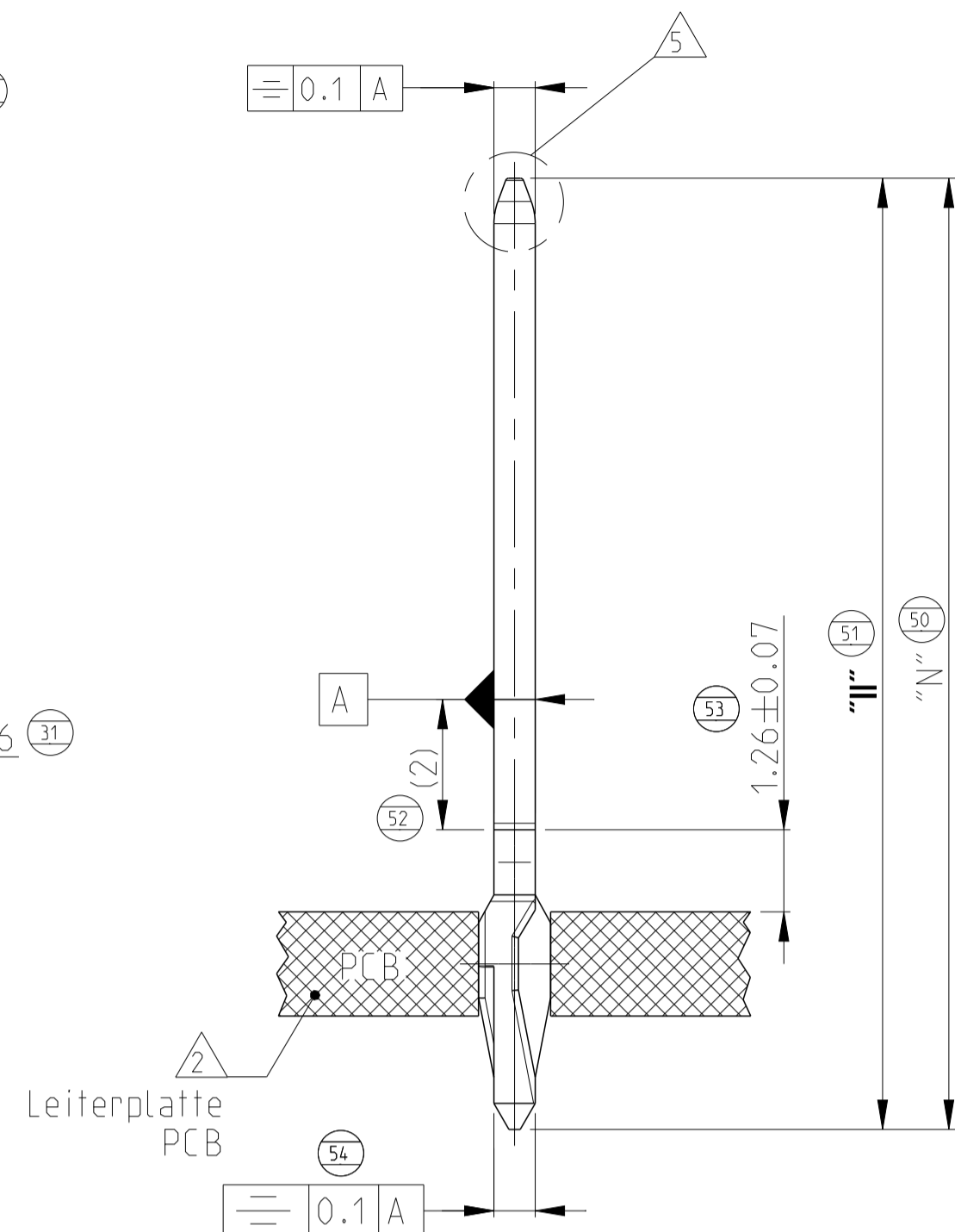
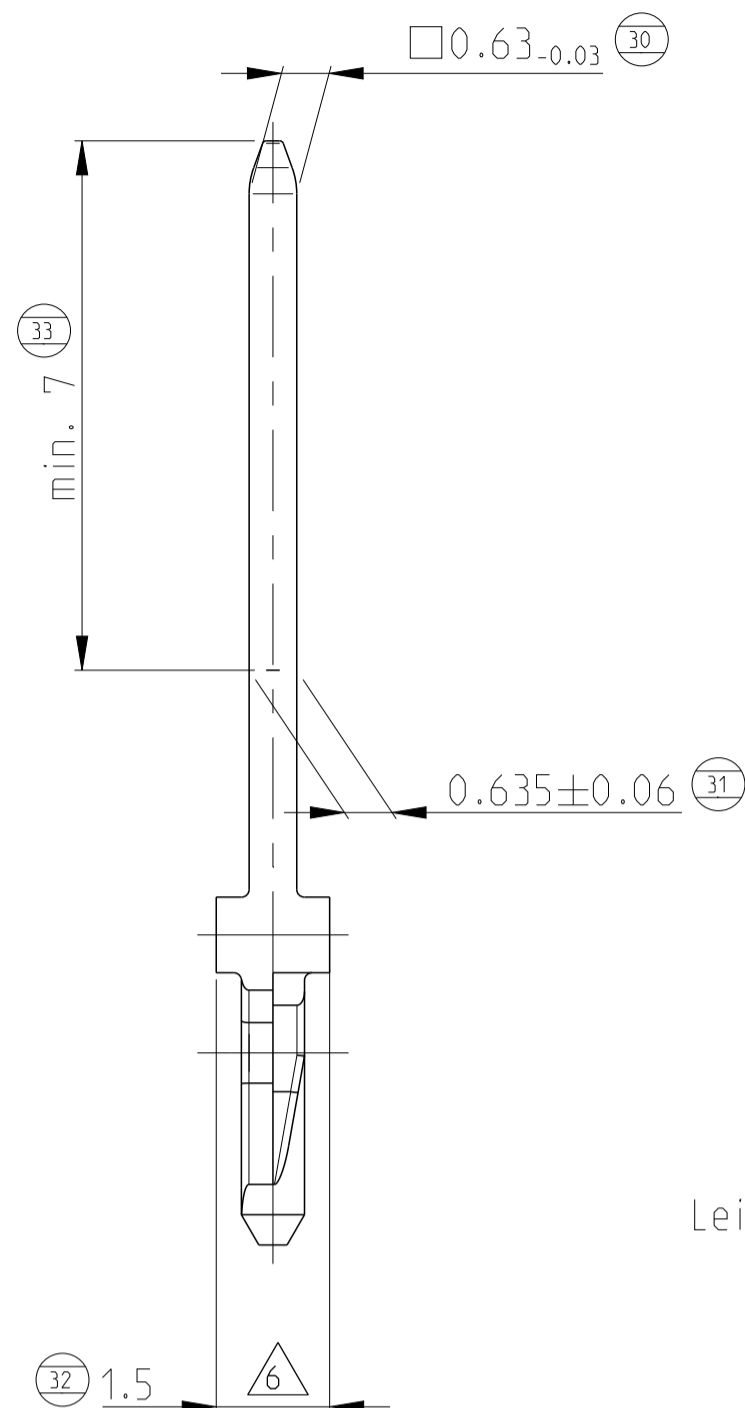
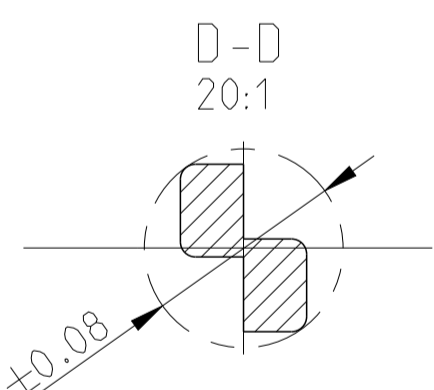
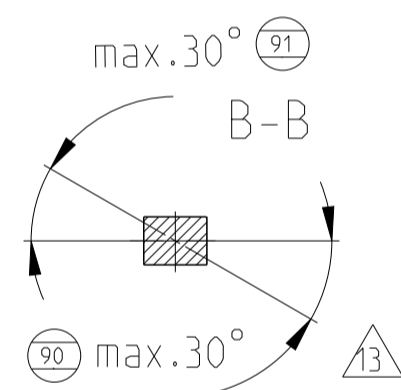


VERSION A

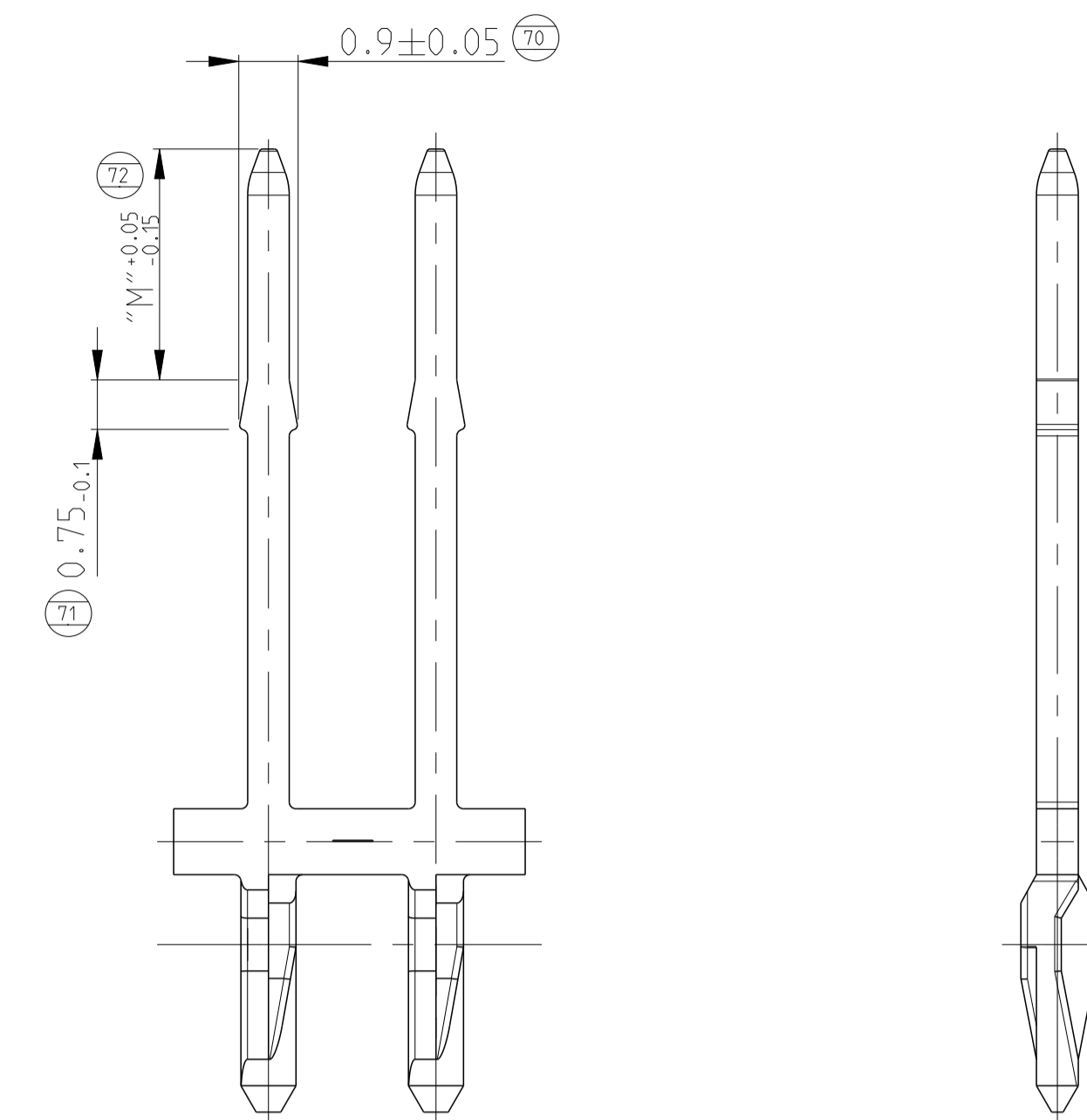


Rastermass, Toleranz pro 30 Kontakte ±0.2
PITCH DIMENSION.TOLERANCES PER 30 CONTACTS ±0.2

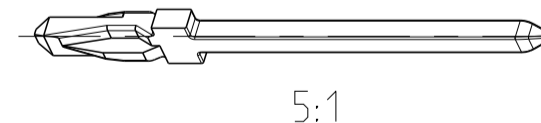


VERSION B

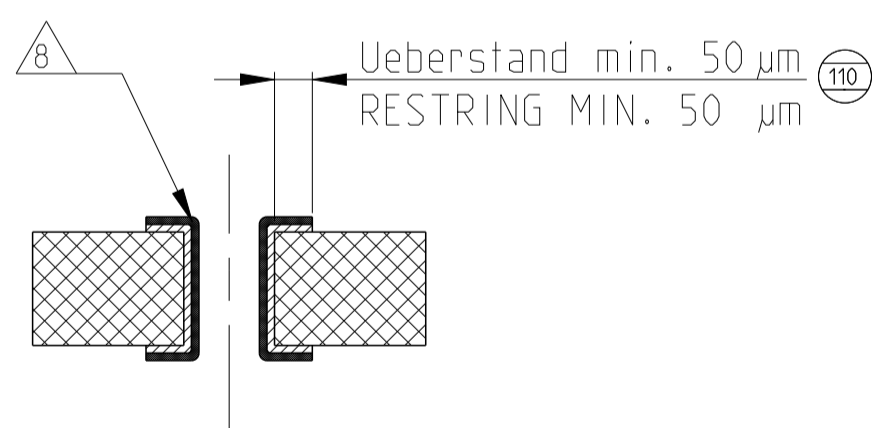
FOR MISSING DIMENSIONS SEE VERSION A



- 1 Massgebend ist der deutsche Text
ONLY THE GERMAN LANGUAGE VERSION SHALL BE BINDING
- 2 Verwendung fuer Leiterplattendicke: 1.6 ±0.14mm
USED ON PCB THICKNESS: 1.6 ±0.14mm
- 3
- 4 Lötbarkeit nach DIN 40046
SOLDERABILITY ACCORDING TO DIN 40046
- 5 Kontaktstift siehe Zeichnung, TE 114-94201 Version B
CONTACT PIN SEE DRAWING TE 114-94201 VERSION B
- 6 Zustand vor dem Einpressen
STATUS BEFORE INSERTION
- 7 Zulaessige Saebelfoermigkeit: 40mm/m
PERMITTED "SABERSHARPNESS": 40mm/m
- 8 Einpresszone fuer 1.6mm Leiterplatte
Anforderung an Leiterplattenloch, siehe Tabelle 1
PRESS-IN AREA FOR 1.6mm PCB
REQUIREMENTS ON PCB HOLE. SEE TABLE 1
- 9 Verpackungseinheit: 50.000 Stck. auf Einweg Kunststoff-Spule Ø 588mm
mit Zwischenlagenpapier, 3 Spulen im Karton
PACKAGING UNIT: 50.000 PCS ON ONE-WAY PLASTIC REEL DIA.588MM
WITH INTERLEAVING PAPER, 3 REELS IN BOX.
- 10 Lochaufbau (Zinn/Blei) in der Leiterplatte (siehe Tabelle 1)
HOLE CONSTRUCT (TIN/LEAD) FOR PCB (SEE TABLE 1)
- 11 Lochaufbau (Nickel/Gold) in der Leiterplatte (siehe Tabelle 1)
HOLE CONSTRUCT (NICKEL/GOLD) FOR PCB (SEE TABLE 1)
- 12 Lochaufbau (Zinn) in der Leiterplatte (siehe Tabelle 1)
HOLE CONSTRUCT (TIN) FOR PCB (SEE TABLE 1)
- 13 Verdrehung Action Pin Spitze max. 30 °
DISTORTION OF ACTION PIN TIP MAX. 30 DEG.
- 14 Material spezifiziert nach UNS C19002
MATERIAL SPECIFIED ACCORDING TO UNS C19002
- 15 Spulen mit Kunststoff-Spule PN 1-1498100-8 mit Zwischenlagenpapier
PN 1-740973-2, Transportkarton 973051-2
REELLED ONTO PLASTIC REEL PN 1-1498100-8 WITH INTERLEAVING
PAPER PN 1-740973-2, SHIPPING CARTON 973051-2
- 16 Spulen mit Spule PN 725654-9 mit Zwischenlagenpapier PN 704973-3.
Transportkarton 973051-2
REELLED ONTO REEL PN 725654-9 WITH INTERLEAVING PAPER PN 704973-3. SHIPPINGCARTON 973051-2
- 17 1.3 µm bis 2.5 µm Nickel nach Formgebung ueber alles
1.3 µm TO 2.5 µm NICKEL UPON PLATING AFTER FORMING SEQUENCE



Lochaufbau in der Leiterplatte HOLE CONSTRUCT FOR PCB



Lochaufbau LP HOLE CONSTRUCT PCB	△10	△11	△12
Kupferschicht COPPER COATING	25-75 µm	25-75 µm	25-50 µm
Zinn/Blei Schicht TIN/LEAD COATING	4-10 µm	-	-
Zinn Schicht TIN COATING	-	-	0.5-1.5 µm
Nickel Schicht NICKEL COATING	-	max. 5 µm	-
Gold Schicht GOLD COATING	-	max. 0.2 µm	-
Bohr Ø HOLE DIA.	1.15±0.025	1.15±0.025	1.15±0.025
Plattierter Ø PLATED DIA.	1 +0.09 -0.06	1 +0.09 -0.06	1.07+0.055 -0.045

Zone "I" AREA	Goldausfuehrung: 0.8 µm bis 2 µm Au ueber Ni GOLD VERSION: 0.8 µm TO 2 µm Au OVER Ni Zinn-Ausfuehrung: 1 µm bis 3 µm Sn TIN-VERSION: 1 µm TO 3 µm Sn SILVER-VERSION 1.5 µm to 5 µm Ag over Ni
Zone "II" AREA	Schichtdicke: 1.3 µm bis 2.2 µm Ni COAT THICKNESS: 1.3 µm TO 2.2 µm Ni FOR PN 8-963964-8 regarding note △17
Zone "III" AREA	Schichtdicke: 0.8 µm bis 1.8 µm Sn ueber Ni COAT THICKNESS: 0.8 µm TO 1.8 µm Sn OVER Ni

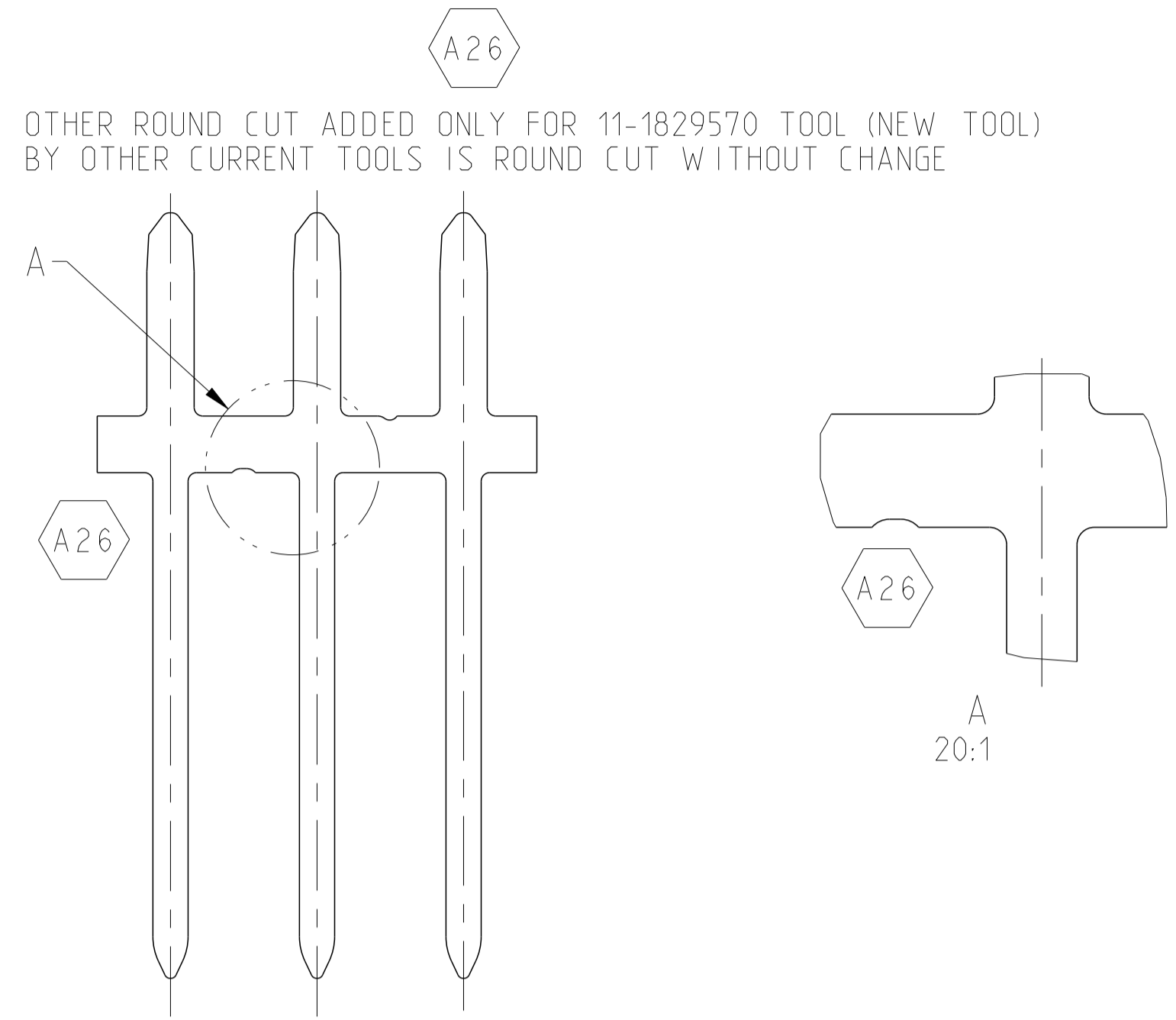
△18 THE PN 8-963964-8 is in development status
The 8-963964-8 is not released for serial production
PN 8-963964-8 ist in dem Entwicklungsstand.
Part number 8-963964-8 ist nicht freigegeben fuer serienproduktion

VERSION	TE CONNECTIVITY BESTELL-NR. ORDER NO.	REV.	MATERIAL	OBERFLAECHE SURFACE AREA "F"	PCB-HOLE SPEC. LP-Bohrung Spez.	GRAMM GEWICHT WEIGHT	"F"	"L"	"M"	"N"
A	7-963964-9	A	CuNiSi R580S	Zinn/TIN	0.05	7	21.3	-	24.9	
	6-963964-5	A		Zinn/TIN		7	11.4	-	15	
	8-963964-7	A		Zinn/TIN		7	11.1	-	14.7	
	2-963964-8	A		Zinn/TIN		7	9.2	-	12.8	
	8-963964-8	A		Silver/Silber		7	11.1	-	14.7	
3-963964-7	A	Gold/GOLD		5.5		11.1	-	14.7		
2-963964-7	A	Zinn/TIN		7		11.1	-	14.7		
2-963964-6	B	Zinn/TIN		7		13.6	7.75	17.2		
2-963964-5	C	Zinn/TIN		8.2		17.8	9.25	21.4		
9-963964-4	A	Zinn/TIN		7		13.6	7.75	17.2		
8-963964-4	A	Zinn/TIN		7		9.8	-	13.4		
3-963964-4	A	Gold/GOLD		5.5		9.8	-	13.4		
2-963964-4	B	Zinn/TIN		7		9.8	-	13.4		
1-963964-4	B	Gold/GOLD		5.5		9.8	-	13.4		
2-963964-3	B	Zinn/TIN		7		8.05	-	11.65		
1-963964-3	B	Gold/GOLD	5.5	8.05	-	11.65				

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER GPS (ISO STANDARDS)		OWN: C. Beu CHK: T. Sieler DATE: 02DEC2002 REV: 10DEC2002	TE Connectivity	
DIMENSIONS: MASSENMEN [mm]	TOLERANCES UNLESS OTHERWISE SPECIFIED: ALIGEMENTSBEREICH	NAME	SIZE	CAGE CODE
0 PLC ±0.5 1 PLC ±0.2 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1	ANGLES/OWNE FINISHOBERFLAECHE/FARB	PRODUCT SPEC MGS ACTION PIN FOR 1mm HOLE ACTION PIN fuer 1mm Loch, freistehend	DRAWING NO. 963964-3	RESTRICTED TO NR FUEH
MATERIAL CuNiSi R580S	WEIGHT GEWICHT	APPLICATION SPEC VERARBEITUNGSSPEZ.	SCALE MASSSTAB 10:1	SHEET BLATT 1 OF 2
CUSTOMER DRAWING		/KUNDENZEICHNUNG		REV A27

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LOC		DIST		REVISIONS			
GT	-	P	LTN	DESCRIPTION	DATE	DWN	APVD
		-		SEE SHEET 1	-	-	-



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN C. Beu	02DEC2002	TE TE Connectivity	
		CHK T. Sieler	10DEC2002		
DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME	
mm		0 PLC ±0.5 1 PLC ±0.2 2 PLC ±0.1 3 PLC ± 4 PLC ±		PRODUCT SPEC	
		ANGLES		APPLICATION SPEC	
		FINISH		SIZE	
MATERIAL CuNiSi R5B0S		FINISH		WEIGHT	
		CUSTOMER DRAWING		SCALE 10:1 SHEET 2 OF 2	

RESTRICTED TO
A1 00779 ©=963964

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